

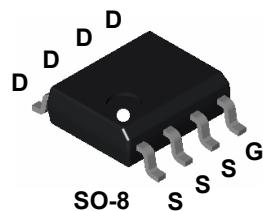
FDS6679AZ

P-Channel PowerTrench® MOSFET -30V, -13A, 9mΩ

General Description

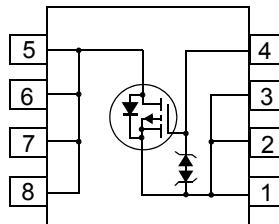
This P-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench process that has been especially tailored to minimize the on-state resistance.

This device is well suited for Power Management and load switching applications common in Notebook Computers and Portable Battery Packs.



Features

- Max $r_{DS(on)} = 9.3\text{m}\Omega$ at $V_{GS} = -10\text{V}$, $I_D = -13\text{A}$
- Max $r_{DS(on)} = 14.8\text{m}\Omega$ at $V_{GS} = -4.5\text{V}$, $I_D = -11\text{A}$
- Extended V_{GS} range (-25V) for battery applications
- HBM ESD protection level of 6kV typical (note 3)
- High performance trench technology for extremely low $r_{DS(on)}$
- High power and current handling capability
- RoHS Compliant



MOSFET Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DS}	Drain to Source Voltage	-30	V
V_{GS}	Gate to Source Voltage	± 25	V
I_D	Drain Current -Continuous (Note 1a)	-13	A
	-Pulsed	-65	
P_D	Power Dissipation for Single Operation (Note 1a)	2.5	W
	(Note 1b)	1.2	
	(Note 1c)	1.0	
T_J, T_{STG}	Operating and Storage Temperature	-55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	50	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction to Case (Note 1)	25	°C/W

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape Width	Quantity
FDS6679AZ	FDS6679AZ	13"	12mm	2500 units

Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
B_{VDSS}	Drain to Source Breakdown Voltage	$I_D = -250\mu\text{A}, V_{GS} = 0\text{V}$	-30			V
$\frac{\Delta B_{VDSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = -250\mu\text{A}$, referenced to 25°C		-20		$\text{mV}/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -24\text{V}, V_{GS} = 0\text{V}$		-1		μA
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 25\text{V}, V_{DS} = 0\text{V}$			± 10	μA

On Characteristics (Note 2)

$V_{GS(\text{th})}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = -250\mu\text{A}$	-1	-1.9	-3	V
$\frac{\Delta V_{GS(\text{th})}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = -250\mu\text{A}$, referenced to 25°C		6.5		$\text{mV}/^\circ\text{C}$
$r_{DS(\text{on})}$	Drain to Source On Resistance	$V_{GS} = -10\text{V}, I_D = -13\text{A}$		7.7	9.3	$\text{m}\Omega$
		$V_{GS} = -4.5\text{V}, I_D = -11\text{A}$		11.8	14.8	
		$V_{GS} = -10\text{V}, I_D = -13\text{A}, T_J = 125^\circ\text{C}$		10.7	13.4	
g_{FS}	Forward Transconductance	$V_{DS} = -5\text{V}, I_D = -13\text{A}$		55		S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = -15\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$		2890	3845	pF
C_{oss}	Output Capacitance			500	665	pF
C_{rss}	Reverse Transfer Capacitance			495	745	pF

Switching Characteristics (Note 2)

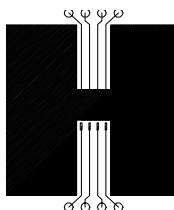
$t_{d(\text{on})}$	Turn-On Delay Time	$V_{DD} = -15\text{V}, I_D = -1\text{A}$ $V_{GS} = -10\text{V}, R_{GS} = 6\Omega$		13	24	ns
t_r	Rise Time			15	27	ns
$t_{d(\text{off})}$	Turn-Off Delay Time			210	336	ns
t_f	Fall Time			92	148	ns
Q_g	Total Gate Charge	$V_{DS} = -15\text{V}, V_{GS} = -10\text{V}, I_D = -13\text{A}$		68	96	nC
Q_g	Total Gate Charge	$V_{DS} = -15\text{V}, V_{GS} = -5\text{V}, I_D = -13\text{A}$		38	54	nC
Q_{gs}	Gate to Source Gate Charge			10		nC
Q_{gd}	Gate to Drain Charge			17		nC

Drain-Source Diode Characteristic

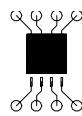
V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = -2.1\text{A}$		-0.7	-1.2	V
t_{rr}	Reverse Recovery Time	$I_F = -13\text{A}, di/dt = 100\text{A}/\mu\text{s}$			40	ns
Q_{rr}	Reverse Recovery Charge	$I_F = -13\text{A}, di/dt = 100\text{A}/\mu\text{s}$			-31	nC

Notes:

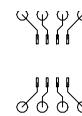
1: $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) 50°C/W when mounted on a 1 in² pad of 2 oz copper



b) 105°C/W when mounted on a .04 in² pad of 2 oz copper



c) 125°C/W when mounted on a minimum pad

Scale 1 : 1 on letter size paper

2: Pulse Test: Pulse Width <300μS, Duty Cycle <2.0%

3: The diode connected between the gate and source serves only as protection against ESD. No gate overvoltage rating is implied.

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

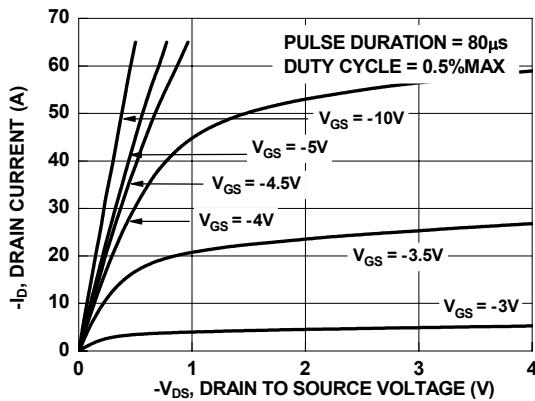


Figure 1. On Region Characteristics

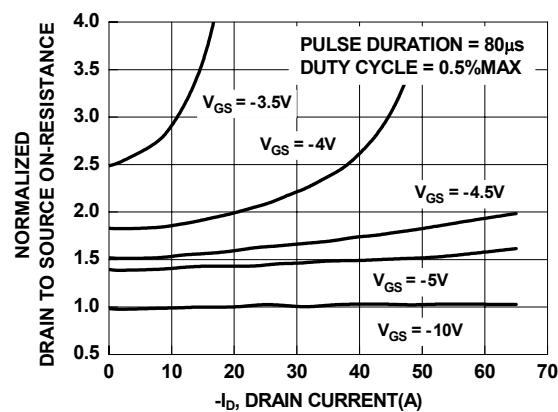


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

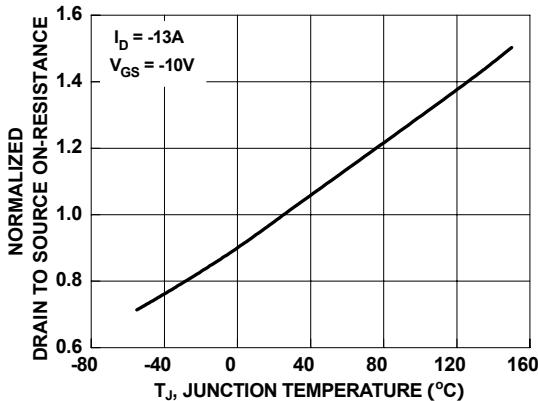


Figure 3. Normalized On Resistance vs Junction Temperature

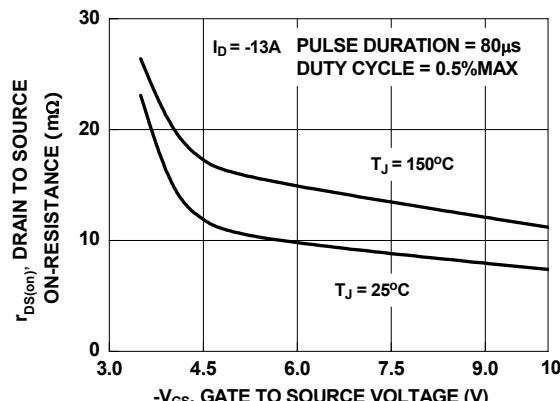


Figure 4. On-Resistance vs Gate to Source Voltage

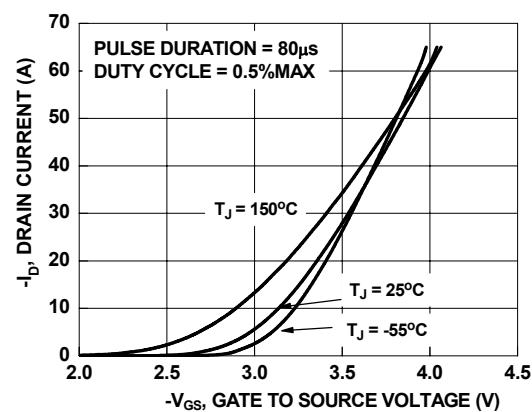


Figure 5. Transfer Characteristics

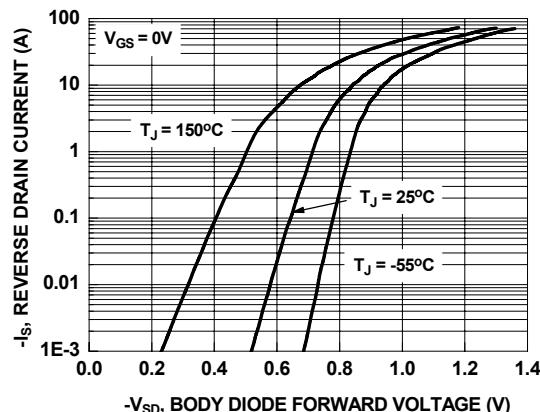


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

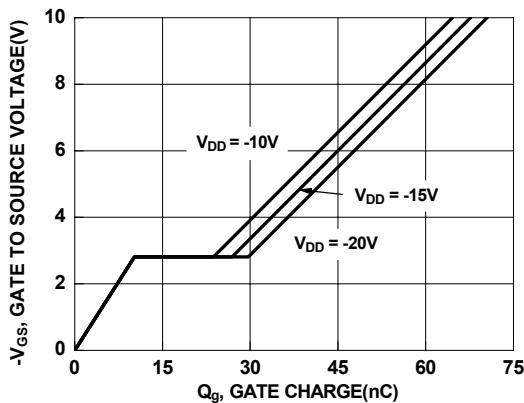


Figure 7. Gate Charge Characteristics

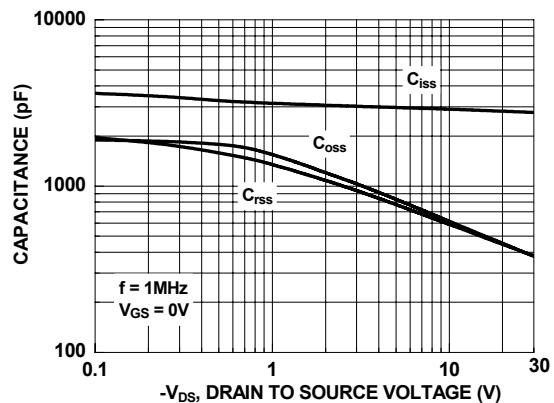


Figure 8. Capacitance vs Drain to Source Voltage

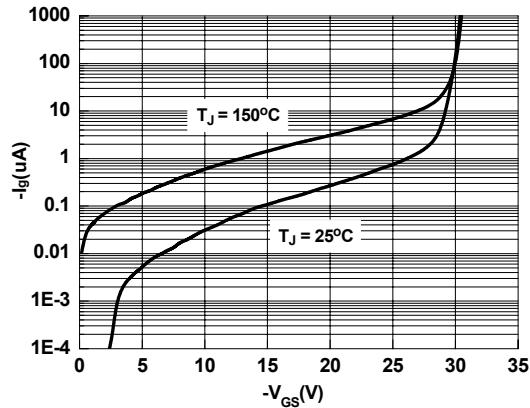


Figure 9. I_g vs V_{GS}

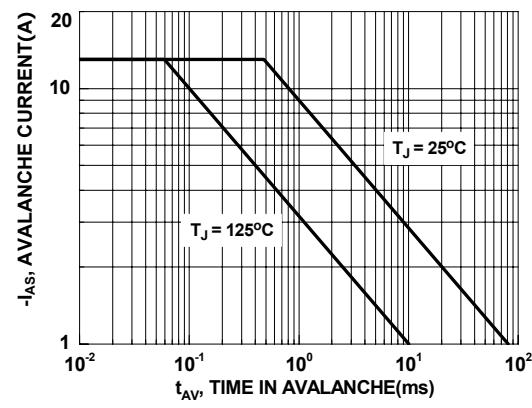


Figure 10. Unclamped Inductive Switching Capability

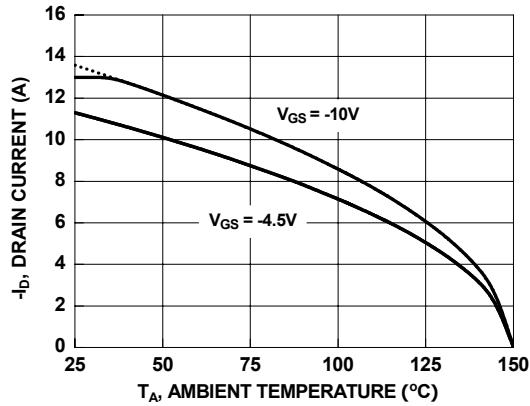


Figure 11. Maximum Continuous Drain Current vs Ambient Temperature

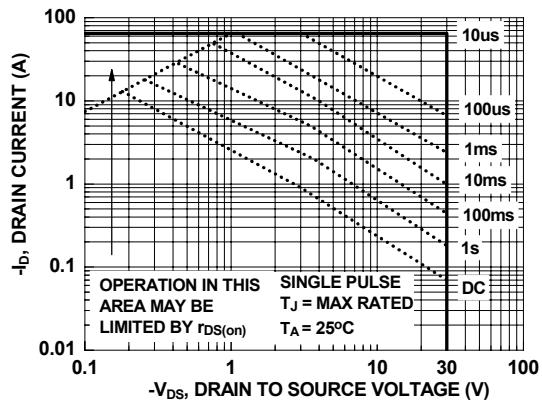


Figure 12. Forward Bias Safe Operating Area

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

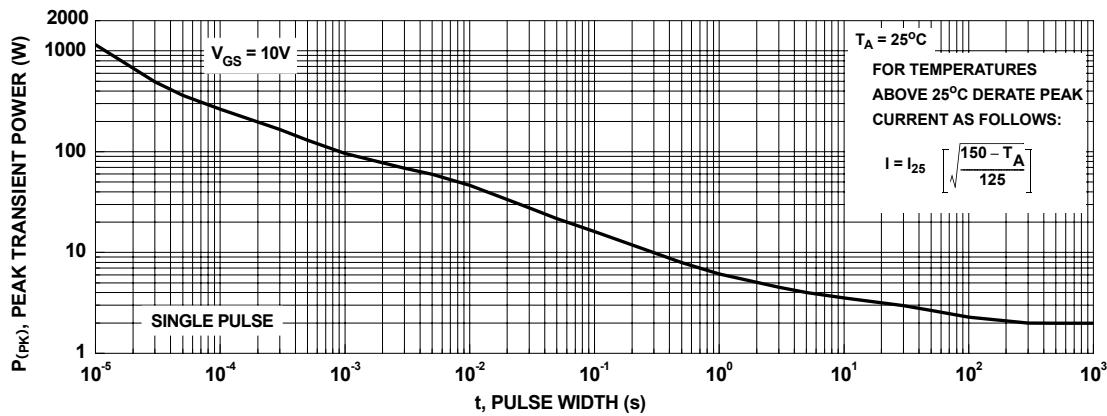


Figure 13. Single Pulse Maximum Power Dissipation

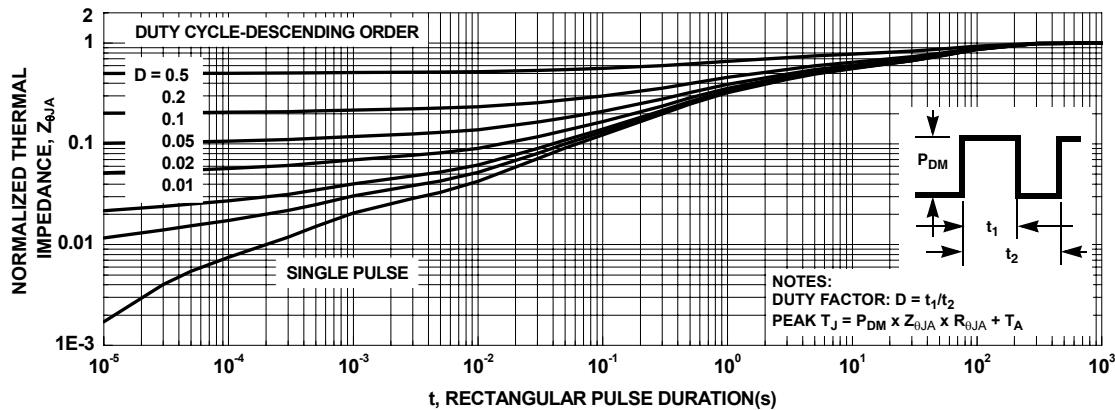


Figure 14. Transient Thermal Response Curve

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